



Lisa Ott Ray, Marketing
7956 Main Street NE
Minneapolis, MN 55432 USA
Phone: 763-277-9711

High-Power Burn-In System For Logic and Memory Devices up to 150-Watts

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(Minneapolis, MN) Micro Control Company announces development of the new HPB-5B High-Power Burn-In System. The HPB-5B was designed to meet the challenges created by burn-in-with-test of both high-power VLSI devices (up to 150 Watts) and memory devices. The HPB-5B also features individual pattern and temperature zones per burn-in board, allowing device types to be mixed within the oven. The HPB-5B provides precise, individual temperature control for up to 48 devices per burn-in board. By controlling the temperature of each device, the HPB-5B manages the wide variations in heat dissipation and the diverse burn-in need that can occur with high-power VLSI devices during the burn-in process. Memory devices can be burned-in with or without individual temperature control, and the HPB-5B's ASIC architecture makes testing memory devices during burn-in easy and efficient.

Features

- Individual pattern zone per burn-in board.
- Individual temperature control for each device under test up to 150 Watts.
- 48 temperature channels per burn-in board.
- Tests devices at a maximum temperature of 150° C.
- Up to 128 digital I/O channels per burn-in board.
- 11 programmable voltage regulators per burn-in board (8 regulators at 100 amps each).
- 800 amps of DUT power available per burn-in board.
- System capacity up to 768 devices.

Micro Control Company has more than 32 years of experience in the electronics industry as a manufacturer of automatic test equipment and burn-in/environmental systems. The HPB-5B's innovative design is part of our commitment to meeting customers' requirements throughout the industry.